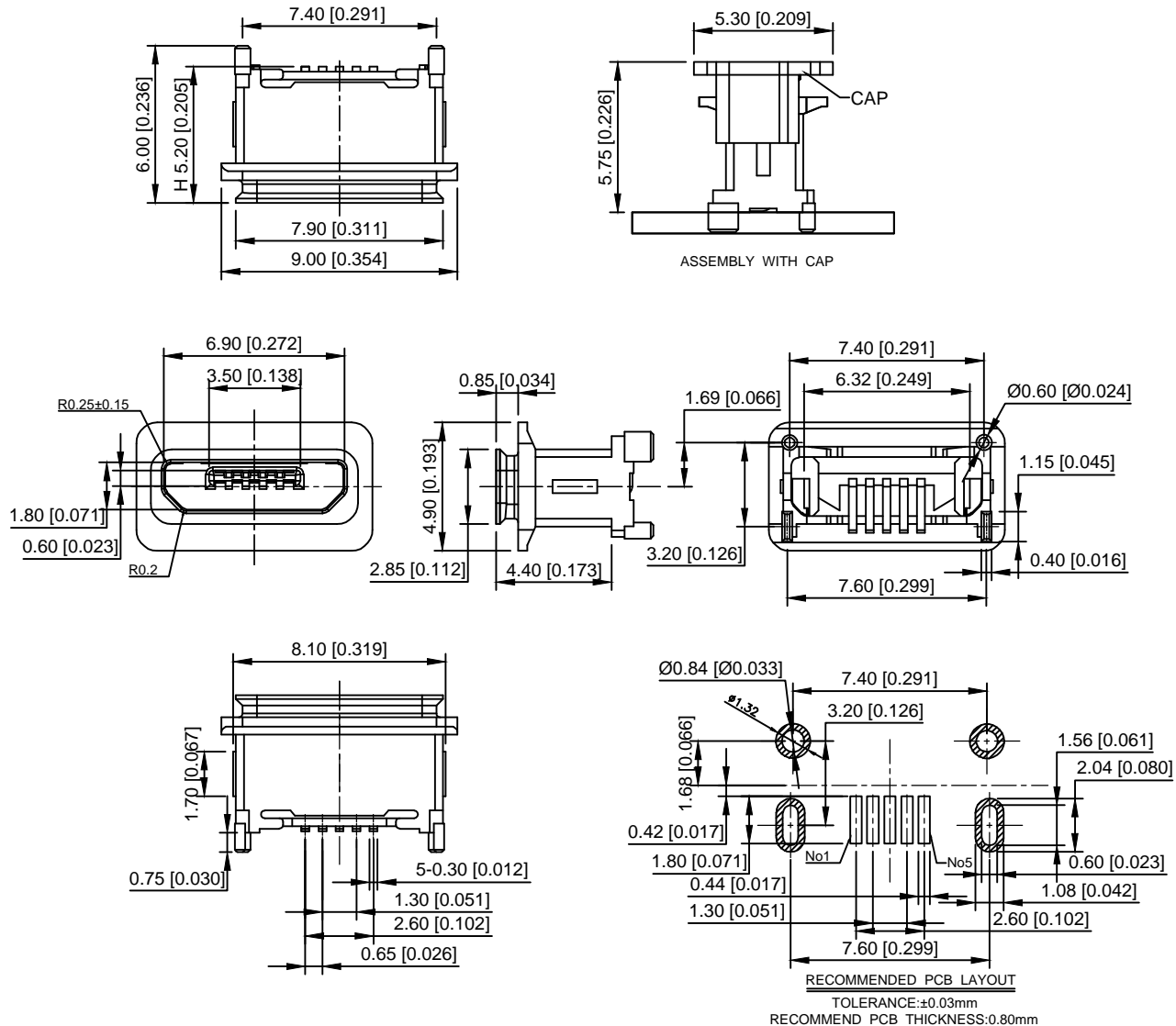


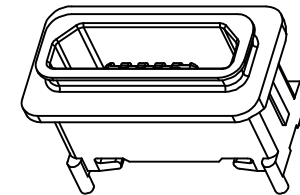
XKB Connectivity



XKB Connectivity

- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC HIGH-TEMP UL94V-0 BLACK COLOR.
 - CONTACT: COPPER ALLOY
 - SHELL: STAINLESS STEEL.
 - FINISH:
 - CONTACT: SEE TABLE 1.
 - OUT SHELL: 50u"Min. NICKEL ALL OVER
 - APPLIED TO IR SOLDERING PROCESS.
 - SPECIFICATION:
 - ELECTRICAL CHARACTERISTICS
 - CONTACT CURRENT RATING: Signal pin 1A, Power pin 1.8A
 - VOLTAGE RATING: 30V AC rms.
 - CONTACT RESISTANCE: 30mΩ MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: UNMATEP CONTACT 100V AC rms. 60MHZ FOR 1 MINUTE.
 - INSULATION RESISTANCE: 1000MQ MIN. 100V DC
 - TEMPERATURE RANGE: -30 TO +85
 - MECHANICAL:
 - INSERTION FORCE: 35N MAX.
 - WITHDRAWAL FORCE: 8N~25N.
 - DURABILITY: 10.000 CYCLES

U-E-M8SS-W-1
 1:G/F 2:5u" 3:10u"
 4:15u" 5:30u"

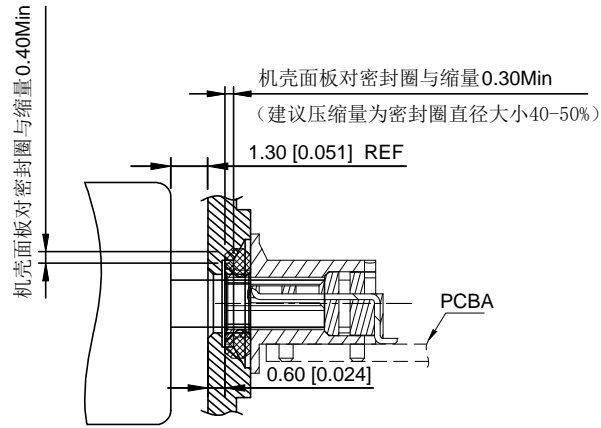


IP-X8

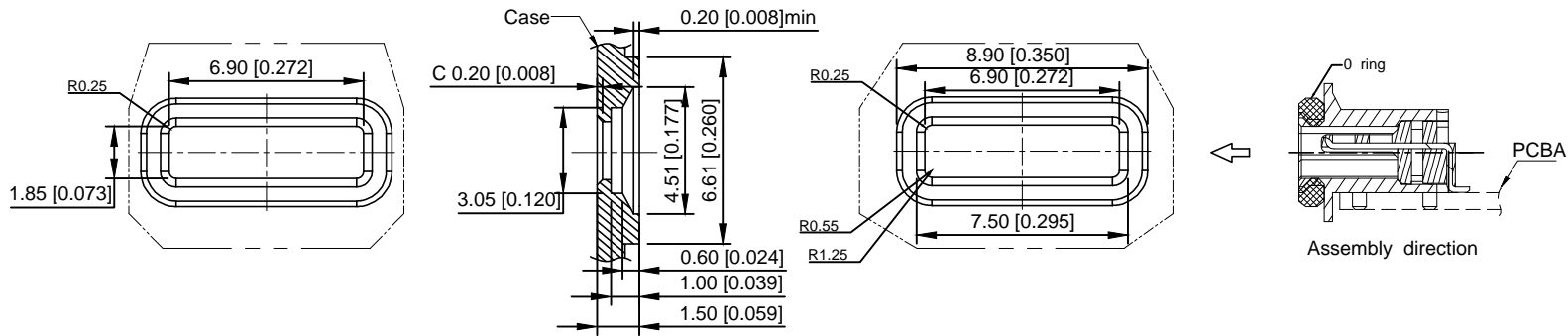
XKB Connectivity

					ANGLAR	±5°	DSND		DATE		SCALE: N/A	MODEL TYPE:
					L ≤ 4	±0.2	DWN		DATE		VIEW:	MICRO USB
					4 < L ≤ 16	±0.3	CHKD		DATE		UNIT: mm/in	PART NO.:
					16 < L ≤ 63	±0.4	APPD		DATE		SIZE: A4	U-E-M8SS-W-1
					L > 63	±0.5						DWG NO.:
					UNSPECIFIED TOLERANCES							U-E-M8SS-W-1
REVISIONS					XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT	SHEET	REVISION		
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn								1.0g	1/1	A0		

XKB Connectivity

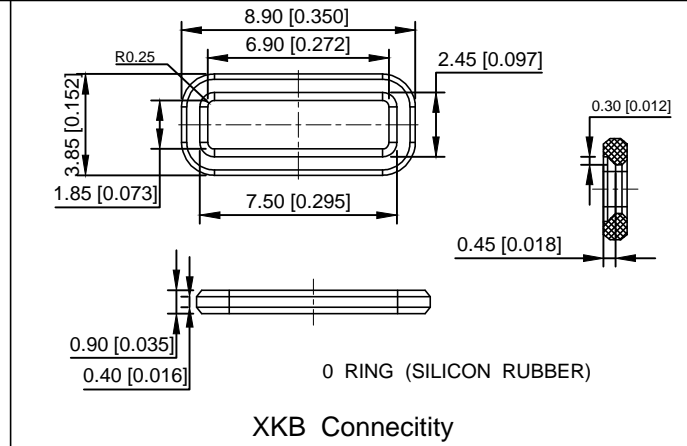


COMPRESSION RATIO TO BE 40%-50%

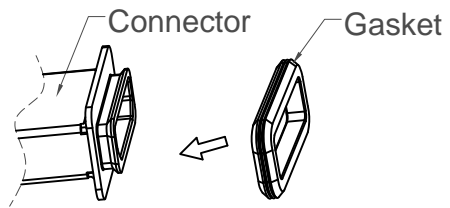


RECOMMENDED OPEN DIMENSION OF CASE

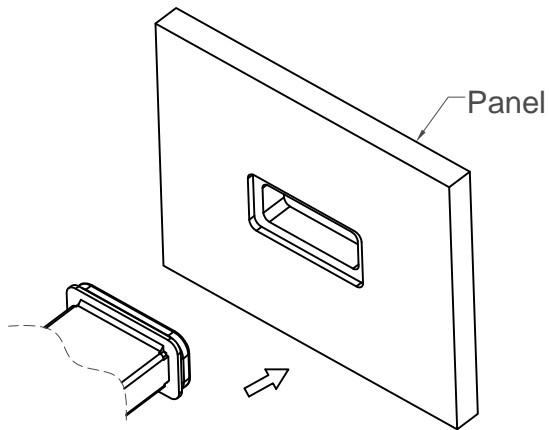
TOLERANCE: ±0.03mm
MATTING AREA WITH SEALING RING



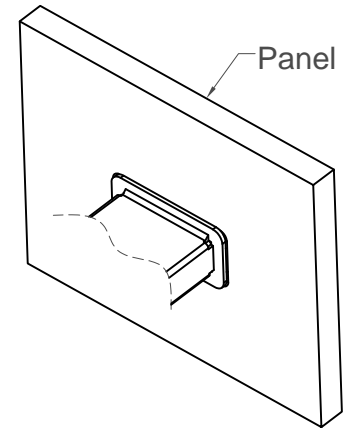
							DSND		DATE		SCALE: N/A	MODEL TYPE: MICRO USB		
ΔX						ANGLAR			DATE		VIEW:	PART NO.: U-E-M8SS-W-1		
ΔX						$L \leq 4$			DATE		UNIT: mm/in	DWG NO.: U-E-M8SS-W-1		
ΔX						$4 < L \leq 16$			DATE		SIZE: A4			
MARK	DESCRIPTION	DATE	REVISED	APPROVED		$16 < L \leq 63$			DATE					
	REVISIONS					$L > 63$								
						UNSPECIFIED TOLERANCES								
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn							XKB INDUSTRIAL PRECISION CO., LIMITED					WEIGHT 1.0g	SHEET 1/1	REVISION A0



Step 1



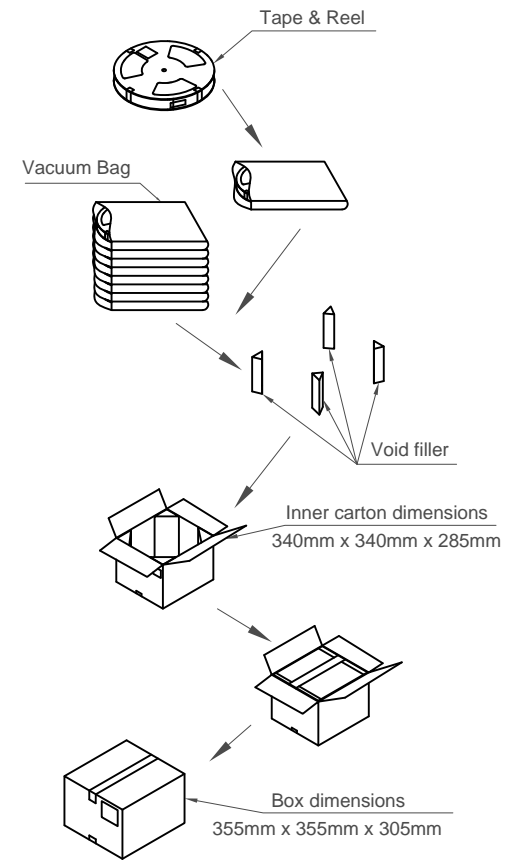
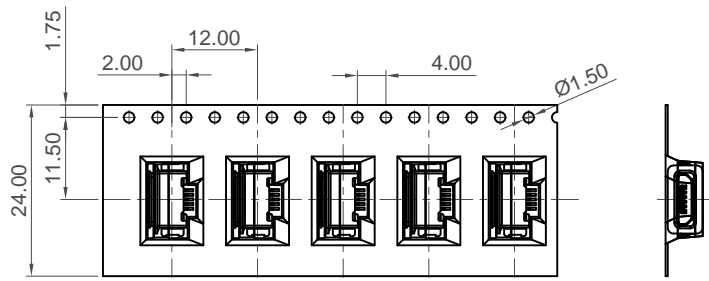
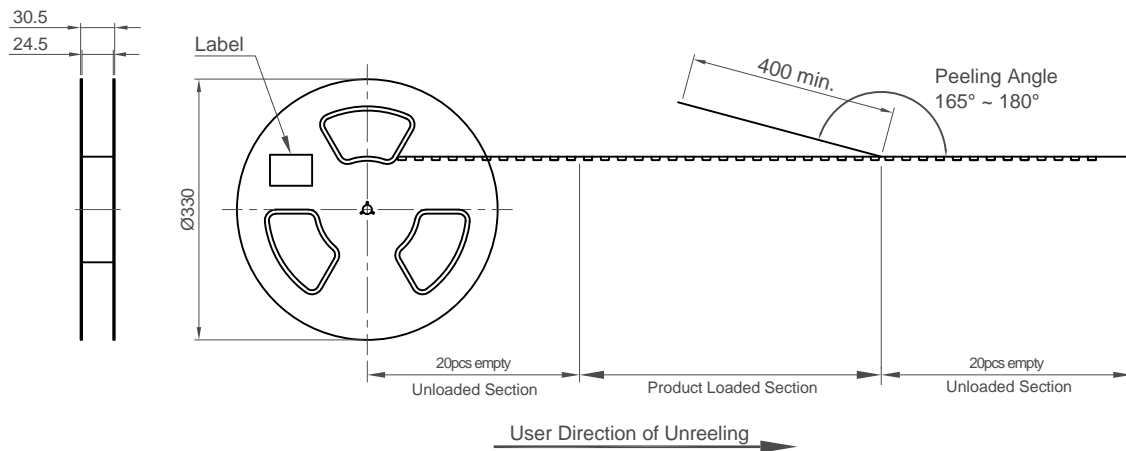
Step 2



Step 3

Assembly instruction for Gasket set after Reflow
Available for Micro USB Waterproof Series

						DSND		DATE		SCALE: N/A	MODEL TYPE: MICRO USB		
						ANGLAR		DATE		VIEW:	PART NO.: U-E-M8SS-W-1		
Δx					$L \leq 4$	± 0.2	CHKD	DATE		UNIT: mm/in	DWG NO.: U-E-M8SS-W-1		
Δx					$4 < L \leq 16$	± 0.3	APPD	DATE		SIZE: A4			
Δx					$16 < L \leq 63$	± 0.4							
MARK	DESCRIPTION	DATE	REVISED	APPROVED	$L > 63$	± 0.5							
REVISIONS						UNSPECIFIED TOLERANCES		XKB INDUSTRIAL PRECISION CO., LIMITED			WEIGHT	SHEET	REVISION
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn											1.0g	1/1	A0



Pcs / Reel	Reels / Carton	Total Quantity
1000	9	9000

Notes:
Peeling off force of top tape: 0.1-1.3N (Peeling direction as shown)

Materials:
Carrier Tape: Polystyrene (PS)
Top Tape: PE
Reel Tape: Polystyrene (PS)
Bag: PE

						DSND		DATE		SCALE: N/A	MODEL TYPE: MICRO USB		
					ANGLAR			DATE		VIEW:	PART NO.: U-E-M8SS-W-1		
					$L \leq 4$	$\pm 5^\circ$		DATE		UNIT: mm/in	DWG NO.: U-E-M8SS-W-1		
					$4 < L \leq 16$	± 0.2		DATE		SIZE: A4			
					$16 < L \leq 63$	± 0.3		DATE					
					$L > 63$	± 0.4		DATE					
MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES								
REVISIONS						XKB INDUSTRIAL PRECISION CO., LIMITED					WEIGHT	SHEET	REVISION
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn											1.0g	1/1	A0